

N-Channel Power MOSFET

450V, 0.5A, 4.25Ω

FEATURES

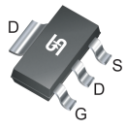
- Low gate charge @typical 6.5nC
- Low Crss @ typical 6.5pF
- Avalanche energy specified
- Improved dV/dt capability
- Pb-free plating
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

APPLICATION

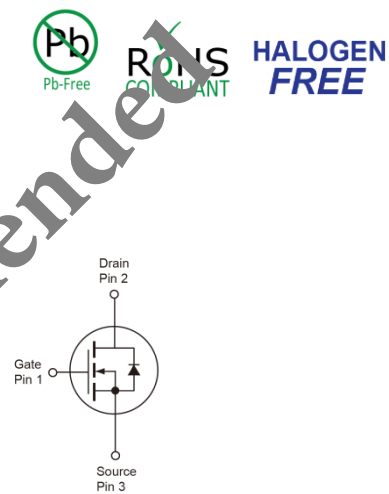
- Power Supply
- Lighting

KEY PERFORMANCE PARAMETERS		
PARAMETER	VALUE	UNIT
V_{DS}	450	V
$R_{DS(on)}$ (max)	4.25	Ω
Q_g	6.5	nC

SOT-223



TO-92



Notes: MSL 3 (Moisture Sensitivity Level) per J-ESD-020

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)				
PARAMETER		SYMBOL	Limit	UNIT
Drain-Source Voltage		V_{DS}	450	V
Gate-Source Voltage		V_{GS}	± 30	V
Continuous Drain Current (Note 1)	$T_C = 25^\circ\text{C}$	I_D	0.5	A
Pulsed Drain Current (Note 2)		I_{DM}	4	A
Total Power Dissipation @ $T_C = 25^\circ\text{C}$	TO-92	P_{DTOT}	2	W
	SOT-223		15	
Single Pulsed Avalanche Energy (Note 3)		E_{AS}	108	mJ
Single Pulsed Avalanche Current (Note 3)		I_{AS}	1.6	A
Repetitive Avalanche Energy (Note 3)		E_{AR}	0.25	mJ
Repetitive Avalanche Current (Note 3)		I_{AR}	0.5	A
Operating Junction and Storage Temperature Range		T_J, T_{STG}	- 55 to +150	$^\circ\text{C}$

THERMAL PERFORMANCE				
PARAMETER		SYMBOL	Limit	UNIT
Junction to Lead Thermal Resistance	TO-92	$R_{\theta JL}$	50	°C/W
Junction to Case Thermal Resistance	SOT-223	$R_{\theta JC}$	8.5	
Junction to Ambient Thermal Resistance	TO-92	$R_{\theta JA}$	140	
	SOT-223		60	

Notes: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. $R_{\theta JA}$ shown below for single device operation on FR-4 PCB with minimum recommended footprint in still air.

Not Recommended

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static ^(Note 4)						
Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	BV _{DSS}	450	--	--	V
Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	V _{GS(TH)}	2.3	--	4.25	V
Gate Body Leakage	V _{GS} = ±30V, V _{DS} = 0V	I _{GSS}	--	--	±100	nA
Zero Gate Voltage Drain Current	V _{DS} = 450V, V _{GS} = 0V	I _{DSS}	--	--	10	μA
Drain-Source On-State Resistance	V _{GS} = 10V, I _D = 0.25A	R _{DS(on)}	--	3.7	4.25	Ω
Dynamic ^(Note 5)						
Total Gate Charge	V _{DS} = 360V, I _D = 0.5A, V _{GS} = 10V	Q _g	--	6.5	10	nC
Gate-Source Charge		Q _{gs}	--	1.3	--	
Gate-Drain Charge		Q _{gd}	--	3.2	--	
Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	C _{iss}	--	235	--	pF
Output Capacitance		C _{oss}	--	29	--	
Reverse Transfer Capacitance		C _{rss}	--	6.5	--	
Switching ^(Note 6)						
Turn-On Delay Time	V _{DD} = 225V, R _{GEN} = 25Ω, I _D = 0.5A, V _{GS} = 10V,	t _{d(on)}	--	14.7	--	ns
Turn-On Rise Time		t _r	--	32.8	--	
Turn-Off Delay Time		t _{d(off)}	--	25.2	--	
Turn-Off Fall Time		t _f	--	23.7	--	
Source-Drain Diode ^(Note 4)						
Maximum Continuous Drain-Source Diode Forward Current		I _S	--	--	0.5	A
Maximum Pulsed Drain-Source Diode Forward Current		I _{SM}	--	--	4	A
Forward On Voltage	I _S = 0.5A, V _{GS} = 0V	V _{SD}	--	--	1.4	V
Reverse Recovery Time	V _{GS} = 0V, I _S = 1A	t _{rr}	--	110	--	ns
Reverse Recovery Charge	di _F /dt = 100A/μs	Q _{rr}	--	0.35	--	μC

Notes:

- Current limited by package.
- Pulse width limited by the maximum junction temperature.
- $L = 75mH, I_{AS} = 1.6A, V_{DD} = 50V, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
- Pulse test: $PW \leq 300\mu s$, duty cycle $\leq 2\%$.
- For DESIGN AID ONLY, not subject to production testing.
- Switching time is essentially independent of operating temperature.

ORDERING INFORMATION

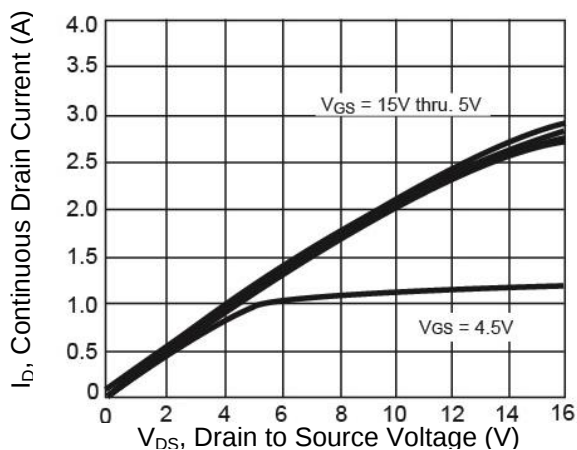
PART NO.	PACKAGE	PACKING
TSM1N45CT B0G	TO-92	1,000pcs / Bulk
TSM1N45CT A3G	TO-92	2,000pcs / Ammo
TSM1N45CW RPG	SOT-223	2,500pcs / 13" Reel

Not Recommended

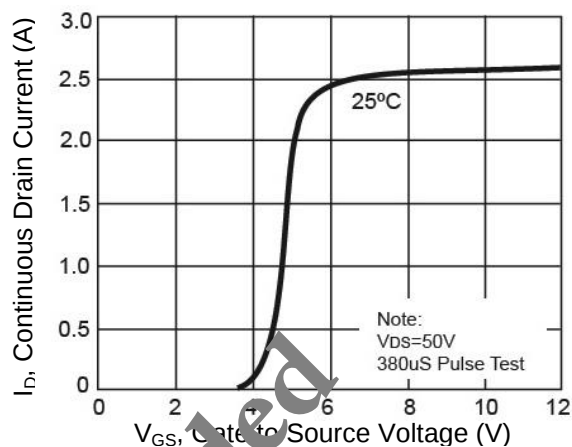
CHARACTERISTICS CURVES

($T_C = 25^\circ\text{C}$ unless otherwise noted)

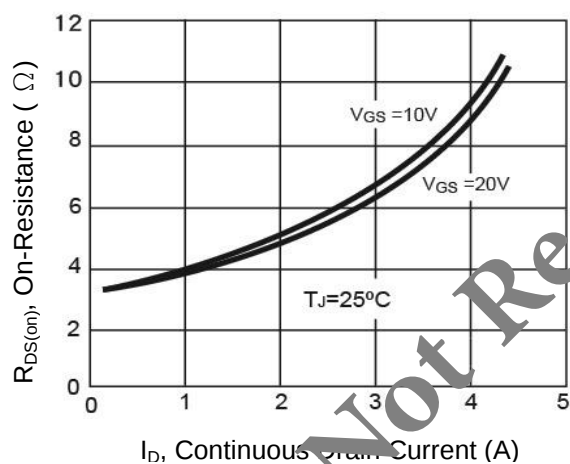
Output Characteristics



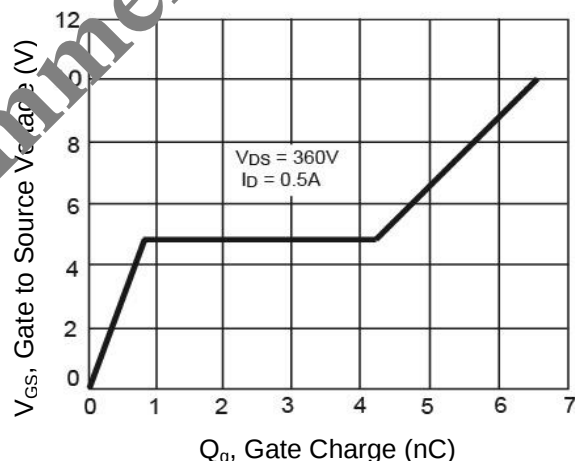
Transfer Characteristics



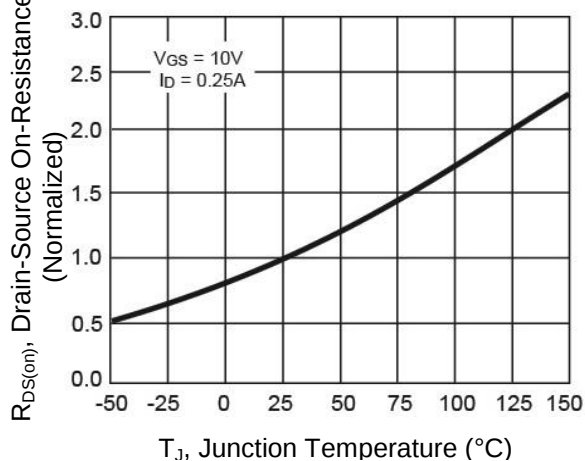
On-Resistance vs. Drain Current



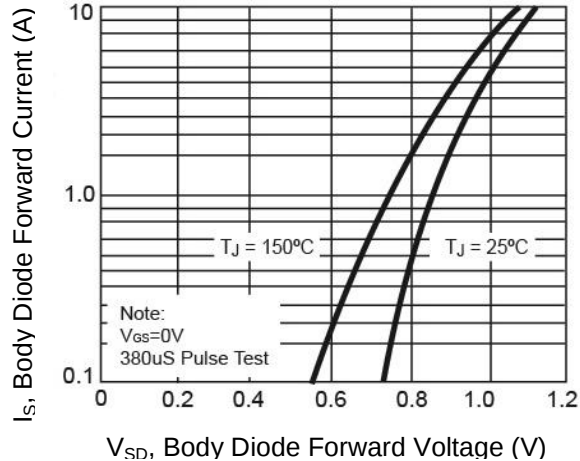
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature



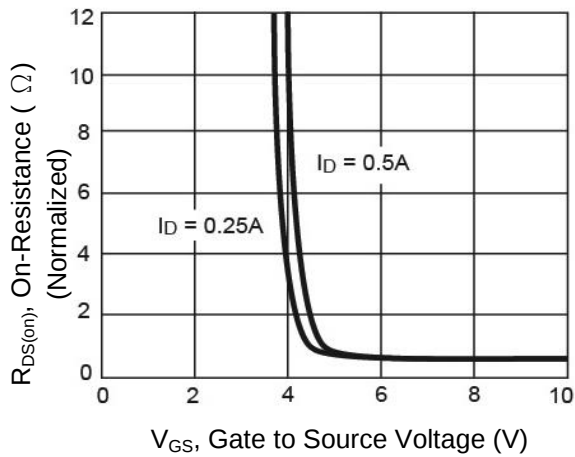
Source-Drain Diode Forward Current vs. Voltage



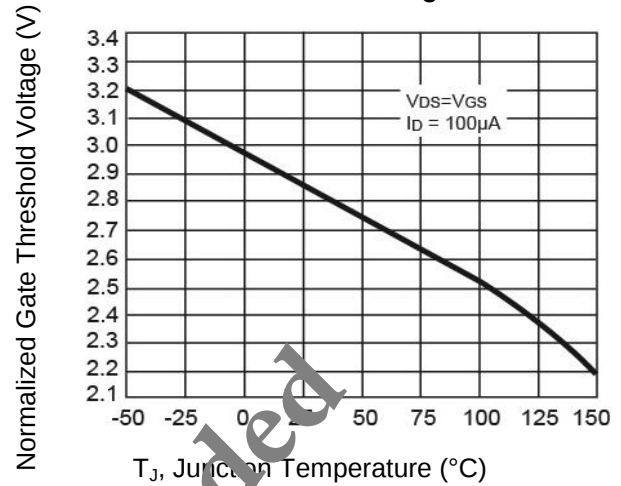
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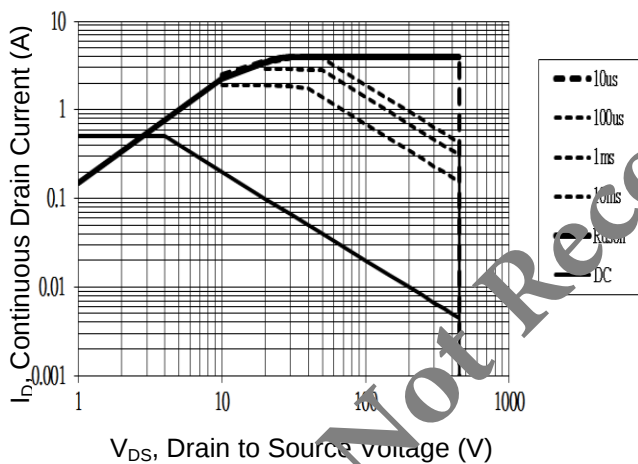
On-Resistance vs. Gate-Source Voltage



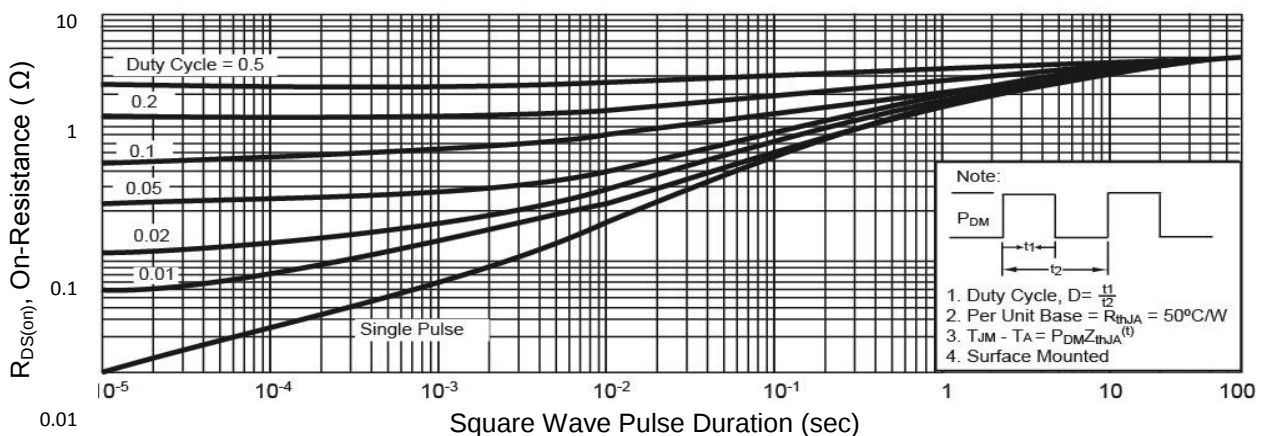
Threshold Voltage



Maximum Safe Operating Area

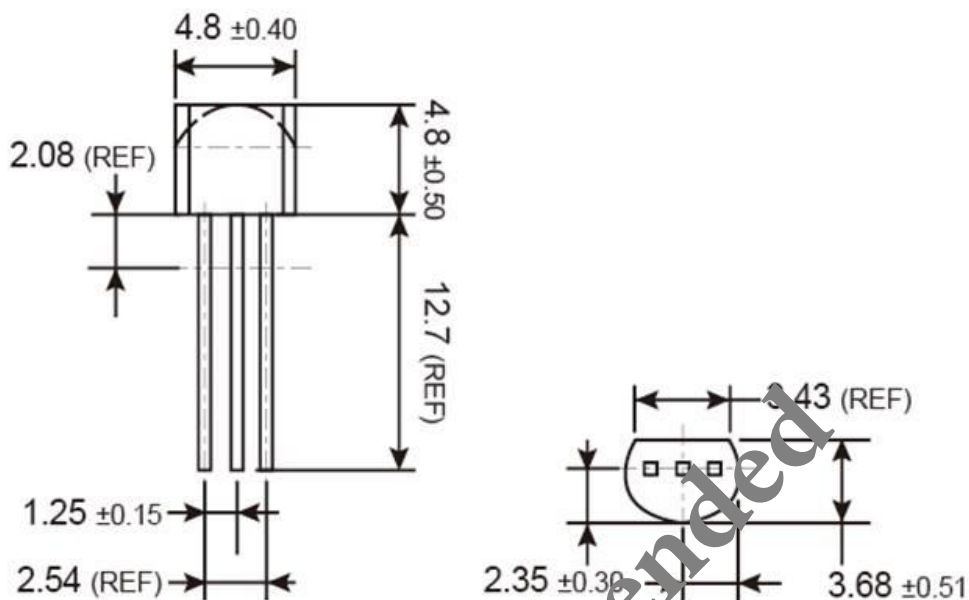


Thermal Transient Impedance, Junction-to-Ambient



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TO-92



MARKING DIAGRAM



Y = Year Code

M = Month Code for Halogen Free Product

O = Jan **F** = Feb **Q** = Mar **R** = Apr

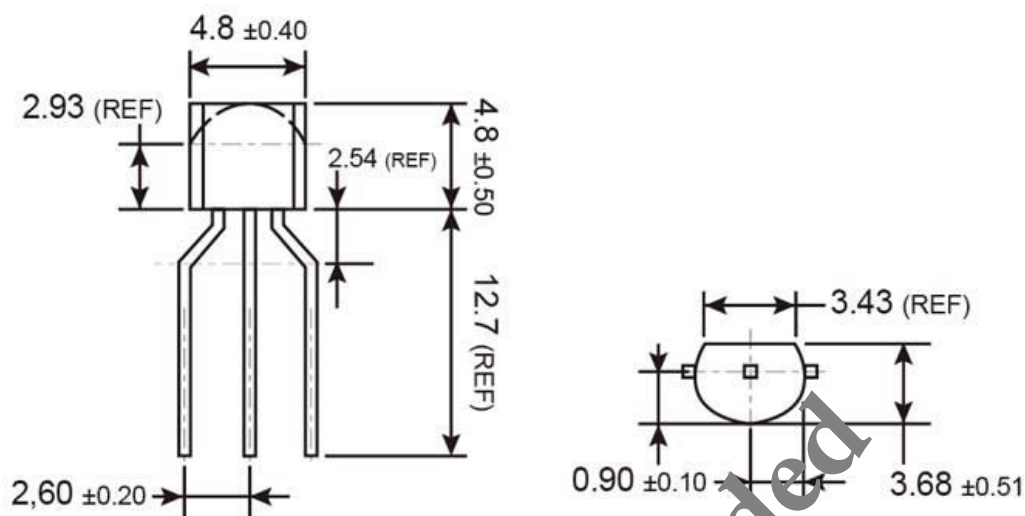
S = May **T** = Jun **U** = Jul **V** = Aug

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L = Lot Code

PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

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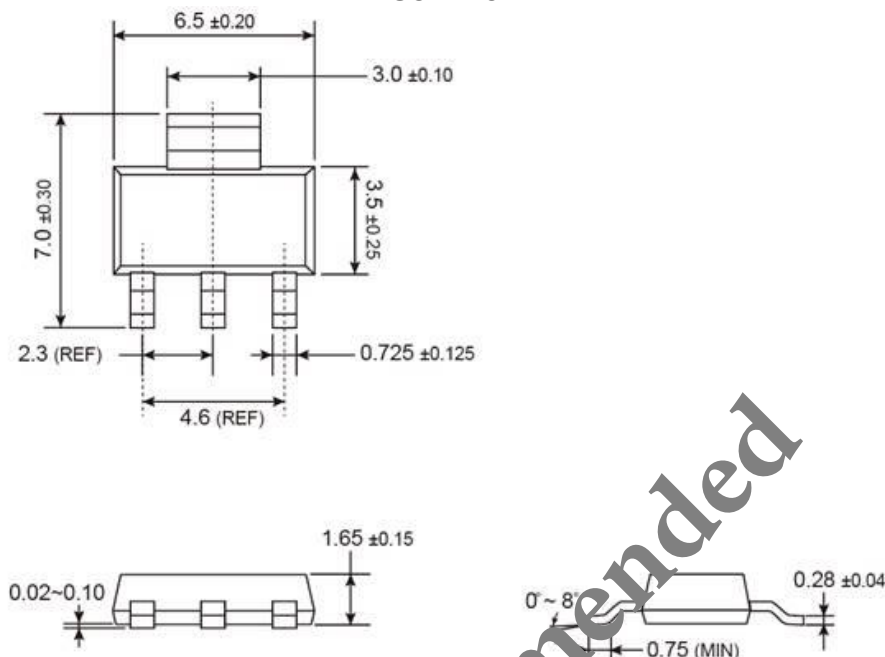
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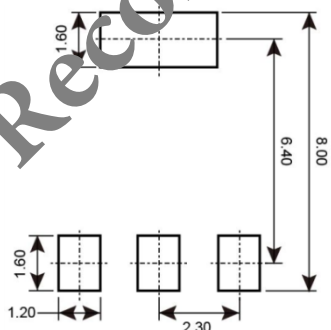
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PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

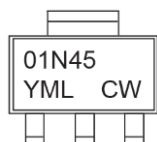
SOT-223



SUGGESTED PAD LAYOUT



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Not Recommended

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